



July 23, 2001

C.B. Cowden  
Compliance Certification Services  
561F Monterey Road  
Morgan Hill, CA 95037-9001

RE: MCPS2135, Power Amplifier system

Dear Chuck,

The following modifications were made to our MCPS2135 power amplifier. These modifications were required to meet the radiated emissions requirements of FCC part 22.

1. Aluminum tape was used to close the second slot opening in the PA module front panel.
2. RF absorber material was added to the backplane assembly (A4E) inside the MCPA modules.
3. Aluminum tape was wrapped around the cover of the A4 BPM Modules to improve their RF shielding.

The aluminum tape used for changes 1 and 3 is 3M Tape 1170, 3/8" wide

The RF absorber added to A4E assembly is: BSR-I/SS-6M

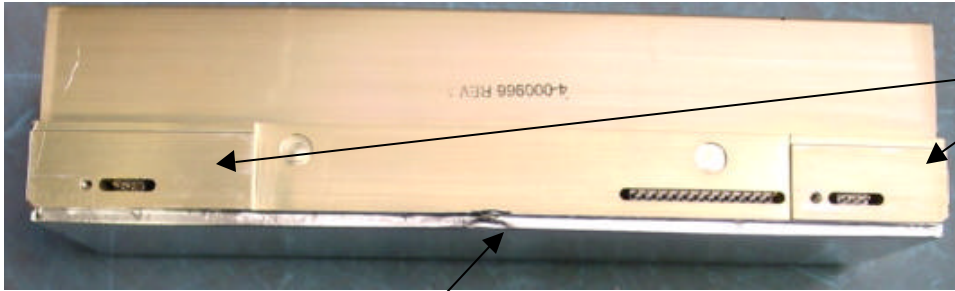
Details of the changes are in the attached rework instruction.

Sincerely,

Charles S. Robertson, III  
Exec. Director of Engineering  
Spectrian, Inc.

## Zeus Brick Rework Instructions

With each BPM removed from the assembly, apply aluminum tape around the edges of the cover on all four sides as shown below. 3/8" tape may be used on the front and sides, and 3/4" tape should be used along the back of the BPM. Be careful not to cover too much of the heatsink fin area. On the back edge of the cover, do not let the tape extend past the back edge of the top of the heatsink. The surface that mates with the backplane should be CLEAN and COMPLETELY FREE OF TAPE.



No tape on this surface

Tape edges as shown

